

FEATURES

Surface Mounting Design 4.5*3.2*2.7mm

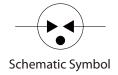
High Current Handling Capability 3000A @ 8/20 µs

Low Capacitance and Insertion Loss

Quick Response and Long Service Life

Moisture sensitivity level: Level 1





APPLICATION INFORMATION

Communication equipment.
Repeaters, Modems
Telephone Interface,Line cards.
Data communication equipment.

AGENCY APPROVALS

lcon	Solderability		
RoHS	Compliance with 2011/65/EU		
HF	Compliance with IEC61249-2-21:2003		
®	Mean lead free		

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated



ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	480-720	
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤ 1300	
impuise spark-over voltage	At 1kV/μs	Typical values of distribution ≤ 1200	
Impulse Discharge Current 2)	8/20µs	3000	
Insulation Resistance	DC=50V	≥ 1	
Capacitance at 1MHz	V _{DC} =0.5V	≤ 1.0	
Operating And Storage Temperature		-40-125	°C

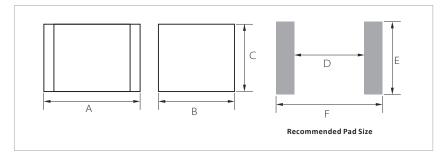
¹⁾ In ionized mode

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards	
High Temperature Storage Test	Temperature: 85°C ; Time:2H	
Low Temperature Storage Test	Temperature: -40°C ; Time:2H	
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min	
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time	

NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

PRODUCT DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref. mm		
А	4.5±0.3mm	
В	3.2±0.3mm	
С	2.7±0.3mm	
D	2.8mm	
E	4.0mm	
F	5.2mm	

²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311 $\,$

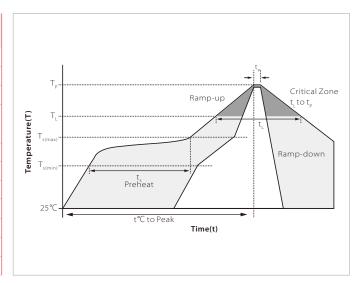


SOLDERABILITY TEST

Solderability		
Solder Pot Temperature	Solder Dwell Time	
245°C ± 5°C	4-6 seconds	

REFLOW PROFILE

Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
	Time(min to max)	60 – 180 secs	
Average ra	amp up rate (Liquidus)Temp (T_L) to peak	3°C/second max	
T _{s(max)} to T _L - Ramp-up Rate		5 C/3eCondinax	
D - A	Temperature (T₁) (Liquidus)	217℃	
Reflow	Time(min to max)(t_s)	60 – 150 seconds	
PeakTemperature (T _p)		260°C	
Time within 5°C of actual peak Temperature (tp)		20-40 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T₂)		8 minutes max.	
Do not exceed		260°C	



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG4532B600H	4.5*3.2*2.7mm	2500PCS	13"



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